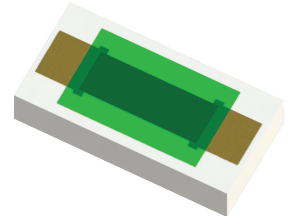


RS2010ZZ-XXXXWN-99-02 Features:

- Single-Sided (Flip-Chip) Terminal Configuration
- Solder, Epoxy or Wirebondable Terminals
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel (Film Side Down) and Waffle Pack Available (Standard is bulk)



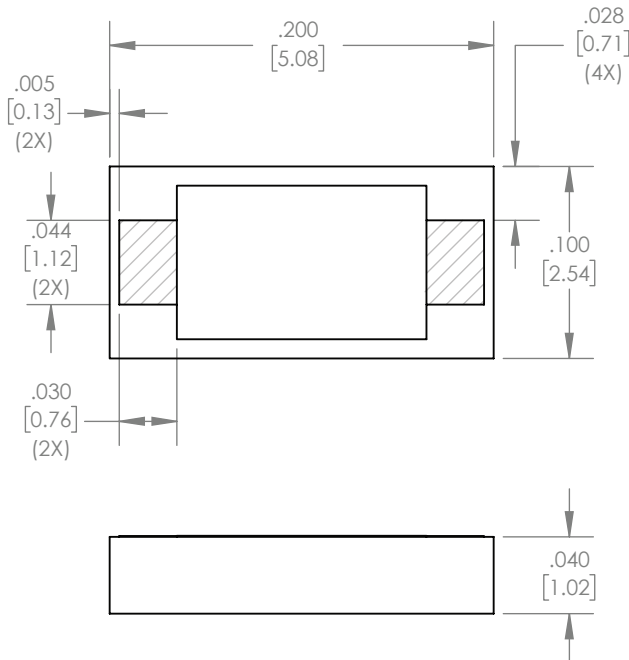
RS2010ZZ-XXXXWN-99-02 Parameters:

Resistance Range: 0.5Ω - 1MΩ
 Rated Power:* 30W
 Construction: Thick Film on 0.040" BeO
 Operating Temperature: -55 to +150°C

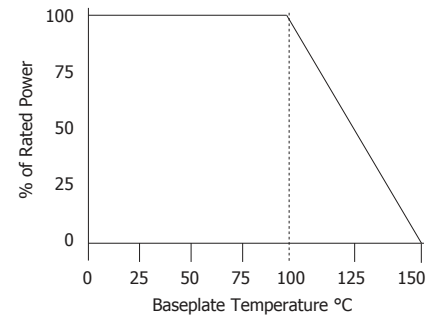
* Rating based on ≤100°C constant baseplate temperature

Actual Size

RS2010ZZ-XXXXWN-99-02 Dimensions:



RS2010ZZ-XXXXWN-99-02 Power Derating Curve



Dimensions in inches [mm]
 Tolerance is ± 0.005 [0.13] unless otherwise stated

Ordering Information:

Example Part Number: RS2010CC-50R0JN-99-02TRD

RS	2010	ZZ	-	XXXX	W	N	-	99	-	02	UU
Prefix for Resistor w/ Single-Sided Terminals	Size	Value Code		Tolerance	Normal Inspection	Substrate	Assigned by Factory	Packaging			
	2010	1000 - 100Ω 1001 - 1KΩ 1002 - 10KΩ 1003 - 100KΩ 1004 - 1MΩ		F - 1% G - 2% J - 5%	Contact factory for additional options	99 - 0.040" BeO		Blank - Bulk WP - Waffle Pack TRD - Tape & Reel			
Terminal Metallization				RoHS	Magnetic	Solder	Epoxy	Wirebond			
AS -	Tin Lead over Platinum Palladium Gold			No	No	Yes	No	No			
CB -	Tin Lead over Nickel over Silver			No	Yes	Yes	No	No			
CC -	100% Matte Tin over Copper over Silver			Yes	No	Yes	No	No			
CT -	100% Matte Tin over Nickel over Silver			Yes	Yes	Yes	No	No			
JA -	Gold over Platinum Palladium Gold			Yes	No	No	Yes	Yes			

Barry Industries reserves the right to change part number and/or process without notification.

RS2010ZZ-XXXXWN-99-02 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +125 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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